

## Features

- Low  $V_F$  Schottky rectifier
- Low profile, typical thickness 0.8mm
- Low leakage current
- Moisture sensitivity: level 1, per J-STD-020
- Heatsink structure
- High temperature soldering guaranteed: 260°C/10 seconds



Package: iSGA  
 (SOD-123HS)



RoHS  
 COMPLIANT

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	GSPS35	GSPS36	Unit
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	50	60	V
Maximum RMS Voltage	$V_{RMS}$	35	42	V
Maximum DC Blocking Voltage	$V_{DC}$	50	60	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	3.0		A
Peak Forward Surge Current (8.3 ms single half sine-wave superimposed on rated load)	$I_{FSM}$	100		A
Rating for Fusing ( $t < 8.3\text{ms}$ )	$I^2t$	41.7		$\text{A}^2\text{sec}$
Operating Junction Temperature Range	$T_J$	-55 to +150		$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 to +150		$^\circ\text{C}$

## Electrical Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Test Conditions	Symbol	Typ.	Max.	Unit	
Minimum Breakdown Voltage	$I_R=1\text{mA}$	$V_{BR}$	60	0.65	V	
Instantaneous Forward Voltage	$I_F=3\text{A}, T_A=25^\circ\text{C}$	$V_F$				
	$I_F=3\text{A}, T_A=125^\circ\text{C}$	$V_F$	0.52	0.60		
Instantaneous Reverse Current at rated DC Blocking Voltage	$T_A=25^\circ\text{C}$	$I_R$	4.1	50	uA	
	$T_A=125^\circ\text{C}$		3.8	10	mA	
Typical Junction Capacitance	4.0 V, 1 MHz	$C_J$	160		pF	
Typical Thermal Resistance	Junction to Ambient	$R_{\theta JA}^{(1)}$	60		$^\circ\text{C/W}$	
	Junction to Lead	$R_{\theta JL}^{(1)}$	6			
	Junction to Case	$R_{\theta JC}^{(2)}$	28			

Note:1) The thermal resistance from junction to ambient or lead, mounted on P.C.B with 5x 5mm copper pads, 2 OZ, FR4 PCB

2) The thermal resistance from junction to case, mounted on P.C.B with recommended copper pads, 2 OZ, FR4 PCB

## Ratings and Characteristics Curves ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

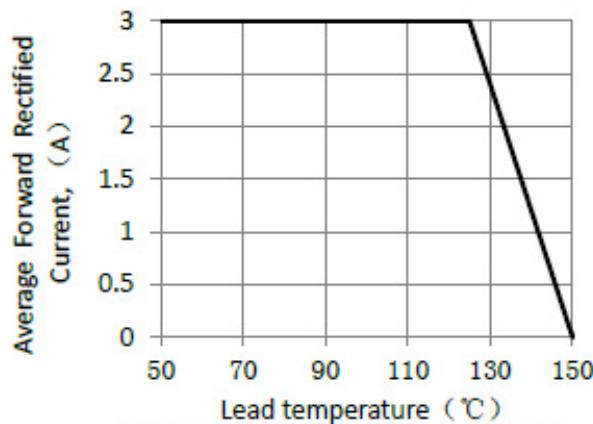


Figure 1. Forward Current Derating Curve

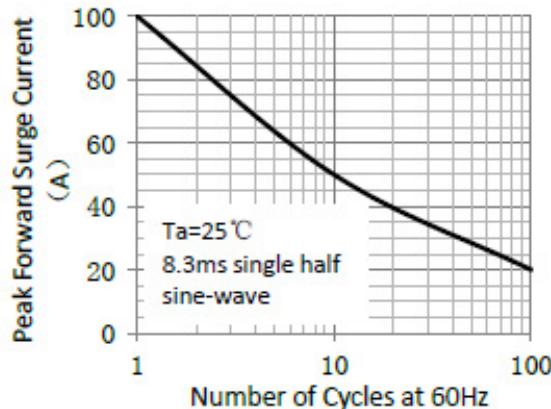


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

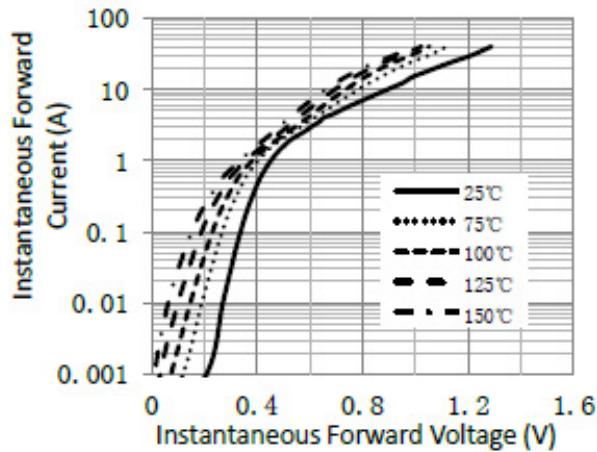


Figure 3. Typical Instantaneous Forward Characteristics

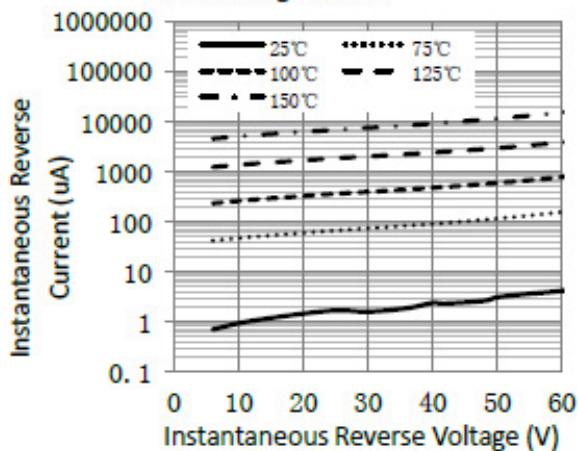


Figure 4. Typical Reverse Characteristics

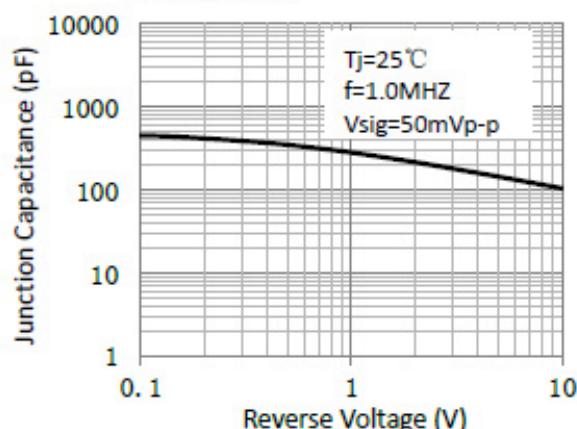
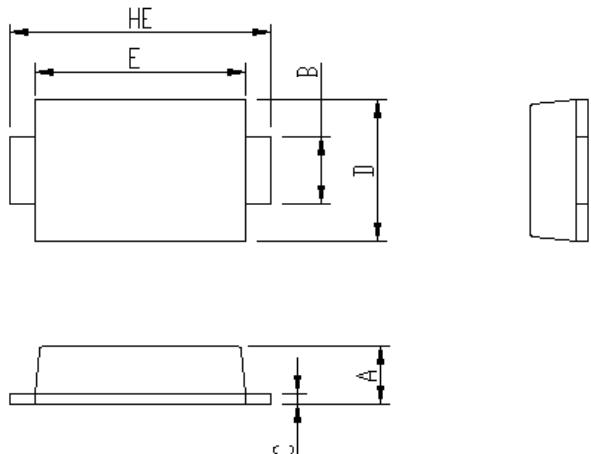


Figure 5. Typical Junction Capacitance

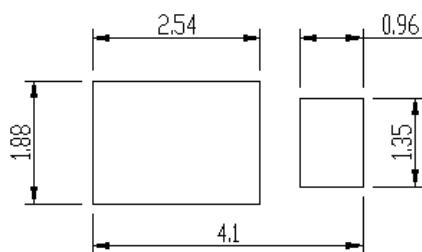
## Package Outline Dimensions

iSGA(SOD-123HS)



Package	iSGA(SOD-123HS)	
Unit:mm	MIN	MAX
A	0.75	0.90
B	0.85	1.05
B1	0.85	1.05
C	0.1	0.25
D	1.9	2.1
E	2.9	3.1
L1	2.0	2.45
L2	0.4	0.85
L3	1.3	1.7
HE	3.5	3.9

Soldering footprint



## Package Information

Reel size	Quantity/reel	Quantity/inner Box	Quantity/Carton
7"	3K	30K	120K

## Tape & Reel Specification

